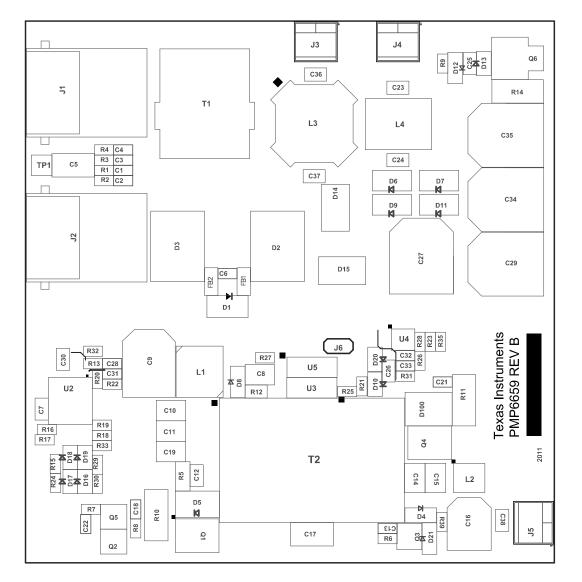
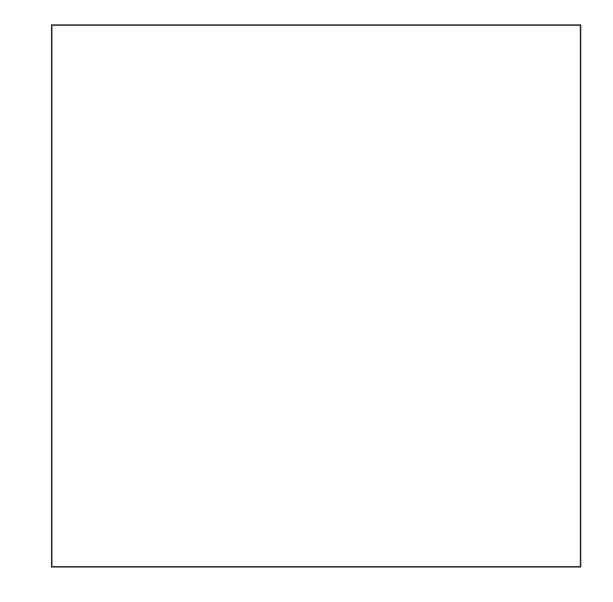
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SVN REV	: Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 1/9/20	14 4:18:52	PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP6659	REV: B	SVN REV:	: Not In VersionControl
	Bottom Overlay <- SNONDI			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 1/9/20	4: 18:52	PM	TEXAS INSTRUMENTS

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